



# 产品规格书

## DP8205(SOT23-6)

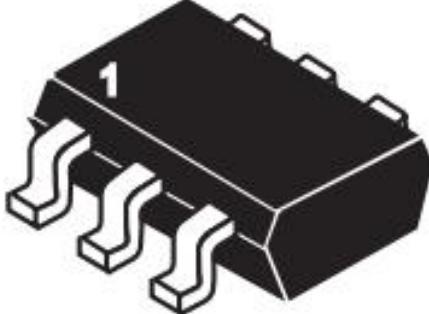
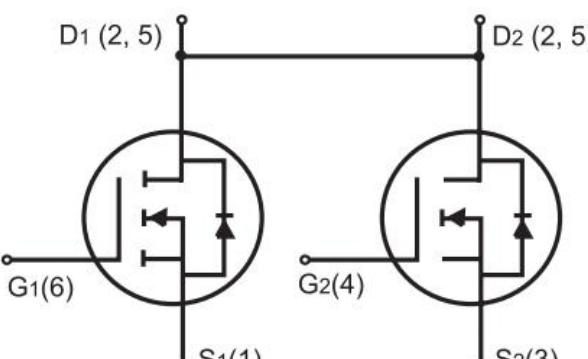
### Datasheet of DP8205(SOT23-6)

深圳市德普微电子有限公司

Shenzhen Developer Microelectronics Co., Ltd.

地址：深圳市南山区高新南四道创维半导体设计大厦西座 707-710 单元  
Address: Unit 7-10, 7/F., west block, Skyworth Semiconductor design Building,  
The 4th on High-tech Zone, Nanshan District, Shenzhen.

General Description	Product Summary
DP8205 uses advanced trench technology to provide excellent $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.	$V_{DS}$ 20 V $I_D$ (at $V_{GS}=4.5V$ ) 5.0A $R_{DS(ON)}$ (at $V_{GS} = 4.5V$ ) < 29mΩ $R_{DS(ON)}$ (at $V_{GS} = 2.5V$ ) < 34mΩ

SOT23-6
 

Absolute Maximum Ratings TA=25°C unless otherwise noted			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous @ $T_J=25^\circ C$	$I_D$	5	A
Pulsed <sup>b</sup>	$I_{DM}$	20	A
Drain-Source Diode Forward Current <sup>a</sup>	$I_S$	2.5	A
Maximum Power Dissipation <sup>a</sup>	$P_D$	1.25	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

Thermal Characteristic			
Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient <sup>a</sup>	$R_{\theta JA}$	100	°C/W

**Electrical Characteristics (TA=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ <sup>c</sup>	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.5	0.7	1.2	V
Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =4.5A	14	20	29	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =3.5A	17	27	34	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =7A	-	17.7	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =8V, V <sub>GS</sub> =0V, F=1.0MHz	-	802	-	pF
Output Capacitance	C <sub>oss</sub>		-	153	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	122	-	pF
<b>Switching Characteristics</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =10V, I <sub>D</sub> =1A V <sub>GS</sub> =4.5V, R <sub>GEN</sub> =10Ω , R <sub>L</sub> =10Ω	-	18	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	43.8	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	20	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =4A, V <sub>GS</sub> =4.5V	-	10.5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	2	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	2.5	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1.7A	-	-	1.2	V

**Notes:**

- a. Surface Mounted on FR4 Board ,T<10 sec ;
- b. Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle ≤ 2%.
- c. Guaranteed by Design, not subject to production testing.

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

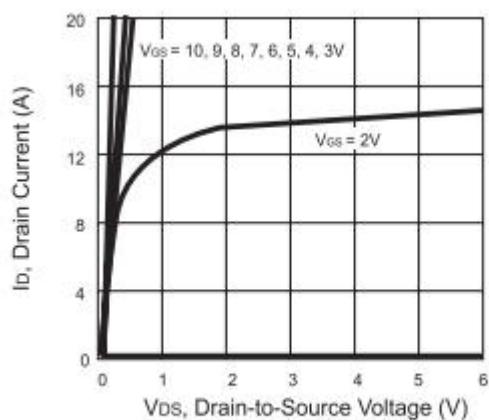


Figure 1. Output Characteristics

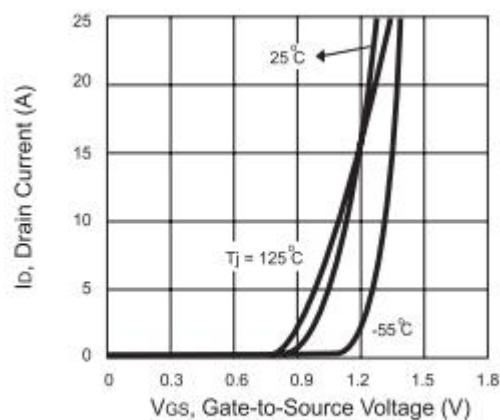


Figure 2. Transfer Characteristics

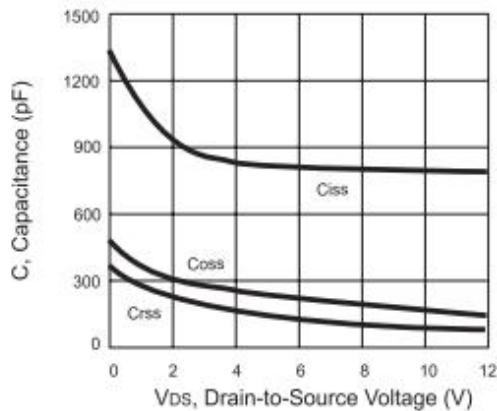


Figure 3. Capacitance

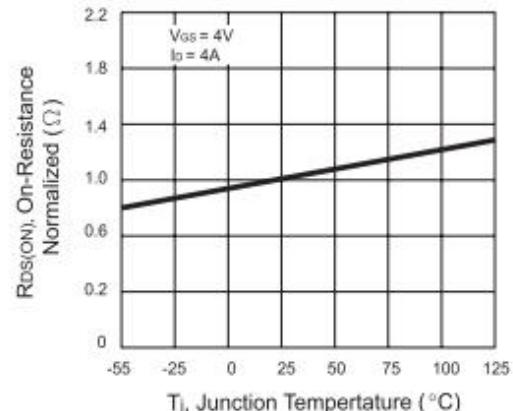


Figure 4. On-Resistance Variation with Temperature

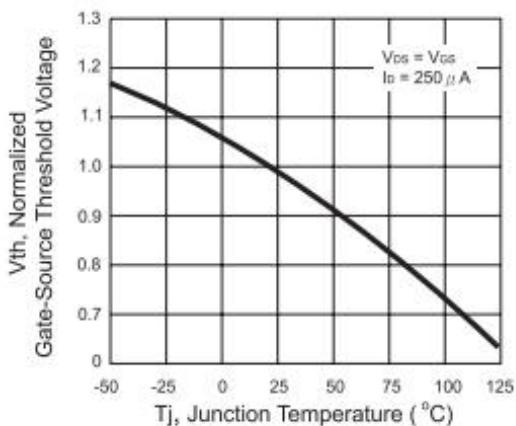


Figure 5. Gate Threshold Variation with Temperature

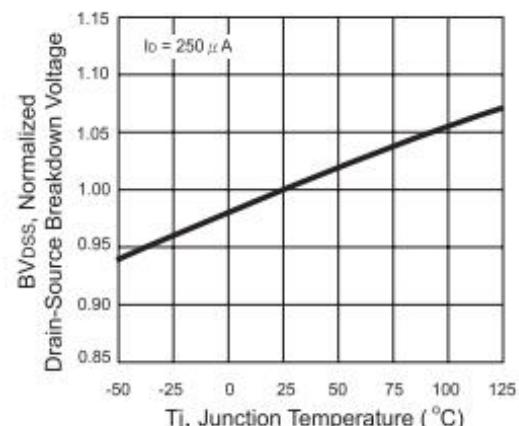


Figure 6. Breakdown Voltage Variation with Temperature

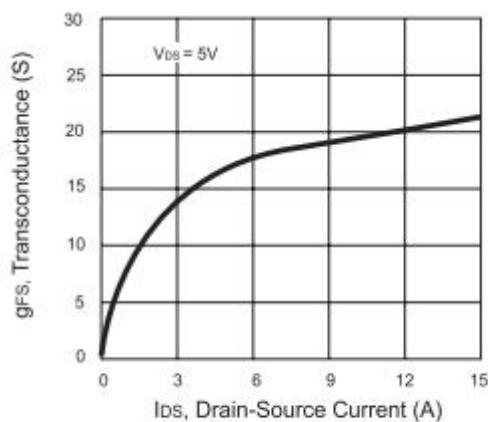


Figure 7. Transconductance Variation with Drain Current

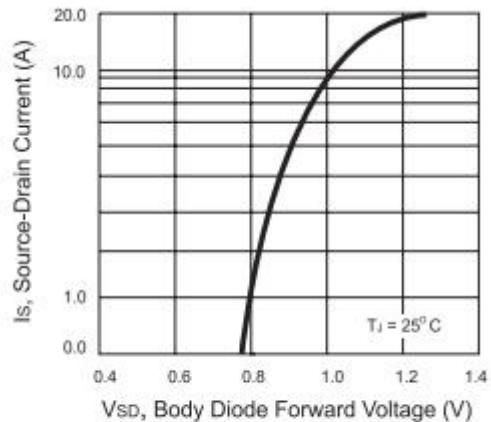


Figure 8. Body Diode Forward Voltage Variation with Source Current

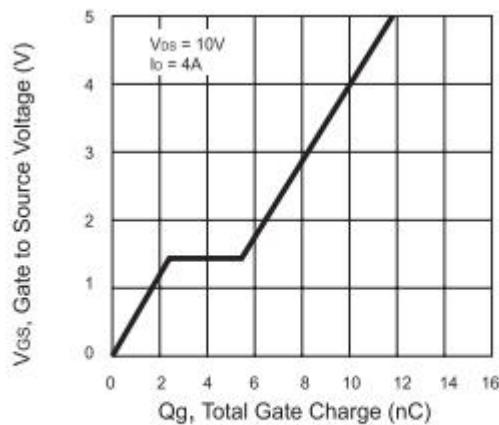


Figure 9. Gate Charge

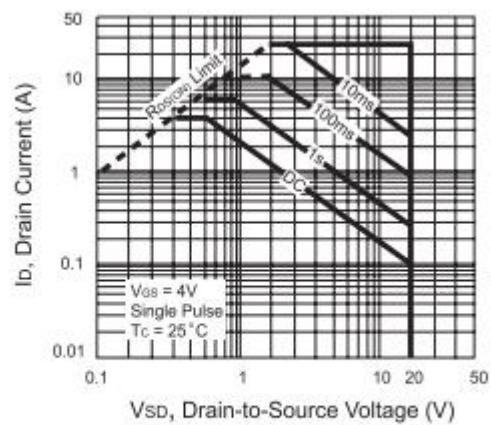


Figure 10. Maximum Safe Operating Area

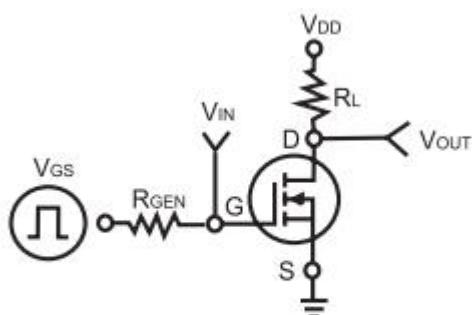


Figure 11. Switching Test Circuit

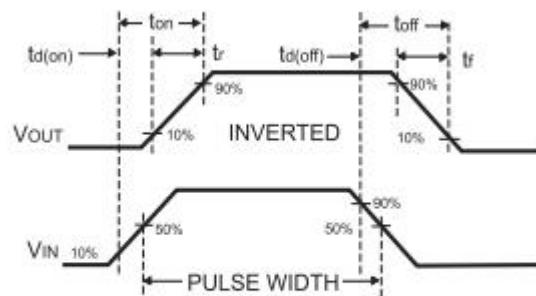


Figure 12. Switching Waveforms

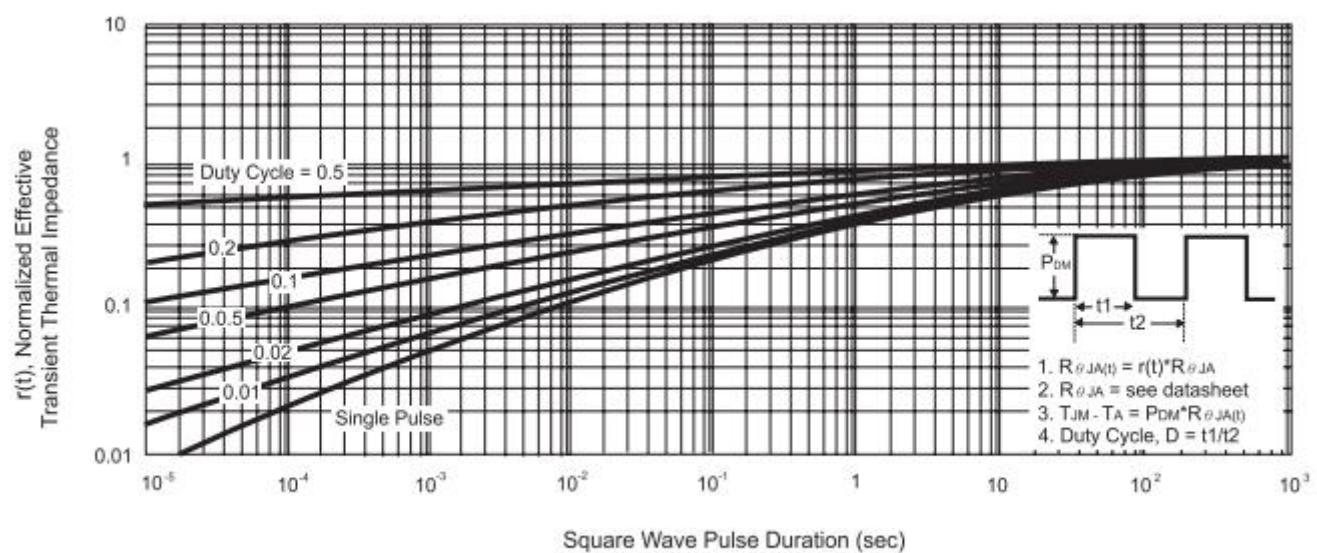
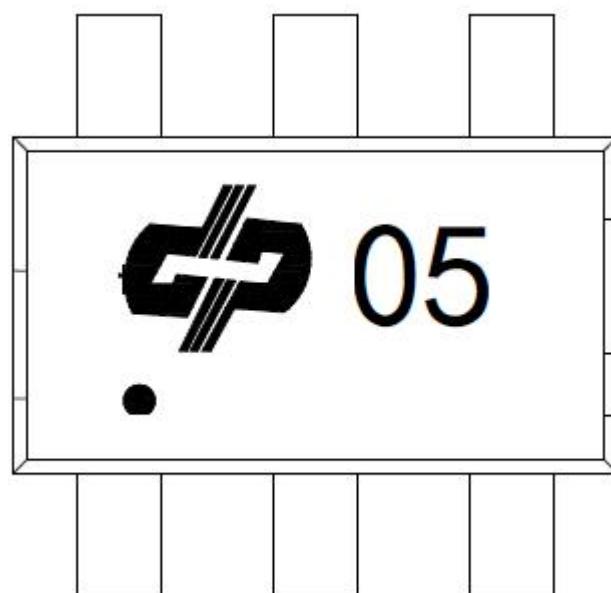
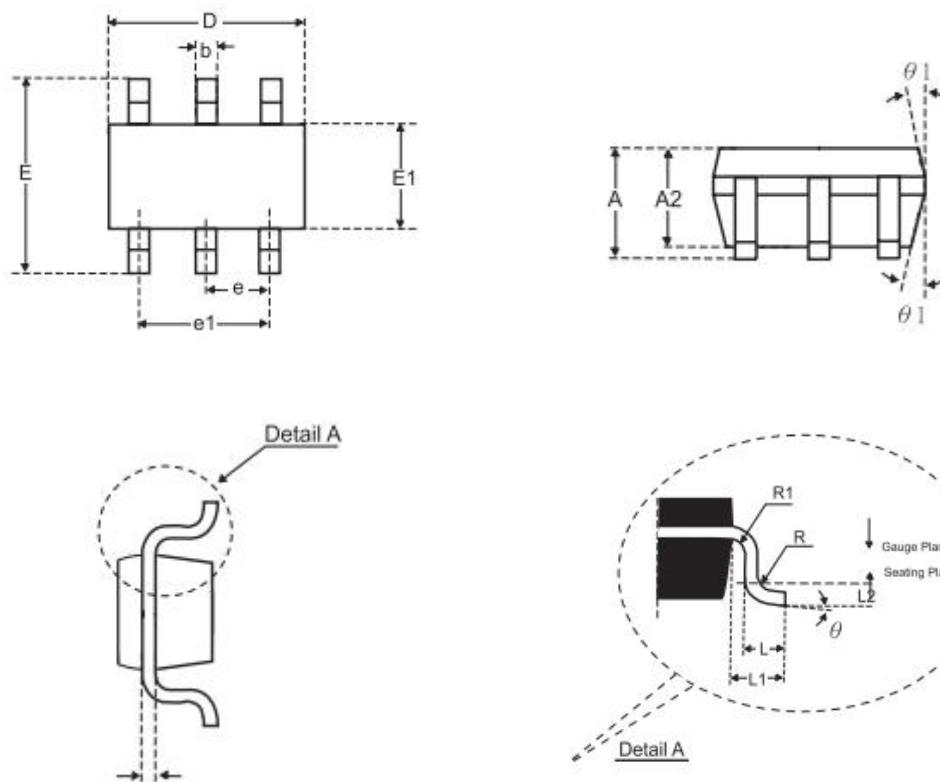


Figure 13. Normalized Thermal Transient Impedance Curve

**MARKINGDESCRIPTION**

**SOT23-6**



**Package Outline Dimensions****SOT23-6**

SYMBOLS	MILLIMETERS		
	Min.	Nom.	Max.
A	-	-	1.45
A2	0.90	0.15	1.30
b	0.30	-	0.50
c	0.08	-	0.22
D	2.70	2.90	3.10
E	2.50	2.80	3.10
E1	1.50	1.60	1.70
e	0.95 BSC		
e1	1.90 BSC		
L	0.30	0.45	0.60
L1	0.60 BSC		
L2	0.20 BSC		
R	0.10	-	-
R1	0.10	-	0.25
θ	0°	4°	8°
θ1	0°	10°	15°